

# APPROVAL SHEET

# **WW25Q**

±1%, ±5%

Metal low ohm power chip resistors
Size 2512 (6432), 1W
RoHS Exemption free and Lead free products
Halogen free
Sensing Type

\*Contents in this sheet are subject to change without prior notice.

#### **FEATURE**

- 1. Ultra low and stable TCR performance
- 2. High power rating and compact size
- 3. High reliability and stability
- 4. Reduced size of final equipment
- 5. RoHS exemption free and Lead free product
- 6. Excellent Heat dissipation and inrush withstand

#### **APPLICATION**

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- Battery charger
- DC-DC power converter

#### **DESCRIPTION**

The resistors are constructed in a high grade low resistive metal body. The structure applies no trimming configuration to provide excellent heat dissipation and inrush withstand capability. The resistive layer is covered with a protective coat and printed a resistance marking code over it. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Lead free terminations.

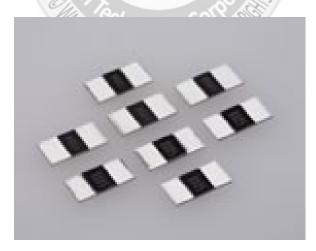


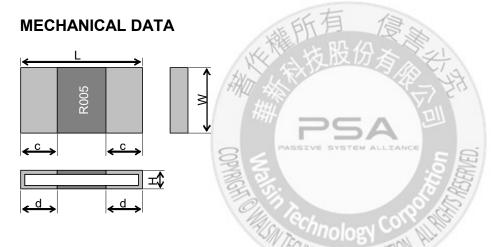
Fig 1. Construction of Chip-R

## **QUICK REFERENCE DATA**

Item	General Specification	
Series No.	WW25Q	
Size code	2512 ( 6432 )	
Resistance Tolerance	±5% , ±1%	
Resistance Range	$2m\Omega$ ~ $10m\Omega$ , $12m\Omega$ , $15m\Omega$	
TCR (ppm/°C)	±100 ppm/°C	
Max. power at T <sub>amb</sub> =70°C	1 W	
Max. Operation Current (DC or RMS)	22.3A ~ 8.1A	
Climatic category (IEC 60068)	55/155/56	

Note: Max. Operation Current: So called RCWC (Rated Continuous Working Current) is determined by

 $RCWC = \sqrt{Rated Power / Resistance Value}$  listed above.



Туре	Size(inch)	Resistance	L(mm)	W(mm)	H(mm)	c(mm)	d(mm)
		2mΩ			0.38±0.15	1.1±	0.25
		3mΩ			0.45±0.15	2.2±	0.25
		4mΩ			0.35±0.15	2.2±	0.25
		5mΩ			0.34±0.15	1.95±0.25	
	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	6mΩ	6.3±0.25		0.34±0.15	1.75	±0.25
WW25Q		7mΩ		3.1±0.25	0.35±0.15	1.4±	0.25
		8mΩ			0.35±0.15	1.1±	0.25
		0.35±0.15	0.8±	0.25			
			0.23±0.15	1.75	±0.25		
		12mΩ			0.23±0.15	1.4±	0.25
		15mΩ			0.23±0.15	0.95	±0.25



#### **MARKING**

Each resistor is marked with a four-digit code on the protective coating to designate the nominal resistance value.

Example:

 $R005 = 0.005\Omega$  $R010 = 0.010\Omega$ 

#### **FUNCTIONAL DESCRIPTION**

### **Derating curve**

The power that the resistor can dissipate depends on the operating temperature; see Fig.2

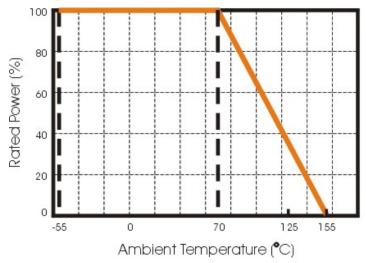


Fig.2 Maximum dissipation in percentage of rated power As a function of the ambient temperature

#### **MOUNTING**

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.



#### **SOLDERING CONDITIONS**

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 2 seconds within lead-free solder bath. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig

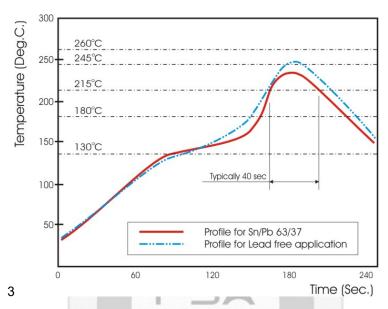


Fig 3. Infrared soldering profile for Chip Resistors WW25Q

#### **CATALOGUE NUMBERS**

The resistors have a catalogue number starting with

WW25	Q	R005	J	Т	L
Size code	Type code	Resistance code	Tolerance	Packaging code	Termination code
WW25 : 2512	Q : 1W	R is first digit followed by 3 significant digits. $0.010\Omega = R010$ $0.005\Omega = R005$	J : ±5% F : ±1%	T:7" reeled in tape	L = Sn base (lead free)

Reeled tape packaging : 12mm width embossed taping 4,000pcs per reel.



# **TEST & REQUIREMENTS (JIS C 5201-1: 1998)**

Table- 4(1)

No.	Test items	Condition of test (JIS C 5201–1)	Performance requirements	
1	Visual examination	Sub-clause 4.4.1 Checked by visual examination.	As in 4.4.1 The marking shall be legible, as checked by visual examination.	
2	Dimension	Sub-clause 4.4.2	As specified in Table-3 of this specification.	
	Resistance	Resistance value shall be measured by mounting the substrate of the following condition.   Current terminal Current terminal Current terminal Copper dad Solder resist a: $3mm (10m\Omega), 2.6mm (5m\Omega), 1.8mm (10m\Omega,15m\Omega)$ Thickness of copper clad: $0.035mm$ 4-Terminal method Measurement current: $1(A)$ Note: The measuring apparatus corresponding to DC Low-ohm Mater (1A) of AX-1152D for ADEX CORPORATION.	As in 4.5.2 The resistance value shal correspond with the rated resistance taking into account the specified tolerance.	
3	Voltage proof	Sub-clause 4.7 Method: 4.6.1.4(See Figure-5) Test voltage: Alternating voltage with a peak value of 1.42 times the insulation voltage. Duration: 60 s±5 s Insulation resistance Test voltage: Insulation voltage	No breakdown or flash over R≥1 GΩ	
		Duration: 1 min.		
4	Solderability	Sub-clause 4.17 Without aging Flux: The resistors shall be immersed in a non-activated soldering flux for 2 s. Bath temperature: 235 °C±5 °C Immersion time: 2 s±0.5 s	As in 4.17.4.5  The terminations shall be covered with a smooth and bright solder coating.	
5	Mounting Overload (in the mounted state)	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3 Sub-clause 4.13 The applied voltage shall be 2.5 times the rated voltage or the current corresponding to. Duration: 2 s		
	Solvent resistance of the marking	Visual examination Resistance Sub-clause 4.30 Solvent: 2-propanol Solvent temperature: 23 °C±5 °C Method 1 Rubbing material: cotton wool Without recovery	No visible damage Δ R ≤ ±1% Legible marking	



Table-4(2)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
6	Mounting	Sub-clause 4.31	·
100	4004.000.000	Substrate material: Epoxide woven glass	
	28 98 13 1958 1858	Test substrate: Figure-4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 1 mm	99
		Resistance	ΔR≤±1%
	Final measurements	Sub-clause 4.33.6	
ō.		Visual examination	No visible damage
7	Resistance to soldering heat	Sub-clause 4.18	
		Solder temperature: 260 °C±5 °C	
		Immersion time: 10 s±0.5 s	
		Visual examination	As in 4.18.3.4
			No sign of damage such as cracks.
	Component solvent	Resistance	ΔR≤±1%
	Component solvent resistance	T COOLETTO	
	resistance	Sub-clause 4.29	
		Solvent: 2-propanol	
		Solvent temperature: 23 °C±5 °C Method 2	
		Recovery: 48 h	No visible damage
		Visual examination	AR < +1%
		Resistance	ΔK21170
8	Mounting	Sub-clause 4.31	
	Wodning	Substrate material: Epoxide woven glass	
		Test substrate: Figure–3	
	Adhesion	Sub-clause 4.32	
		Force: 5 N	
		Duration: 10 s±1 s	2002 200720 70
	100 - 100 - 100 - 100 - 100 - 100	Visual examination	No visible damage
	Rapid change temperature	Sub-clause 4.19	Control Control Control Control
	110 SECT NO	Lower category temperature:-55 °C	
		Upper category temperature:+155 °C	
		Duration of exposure at each temperature: 30	
		min.	
		Number of cycles: 5 cycles.	M. T. T. I
		Visual examination	No visible damage
		Resistance	ΔR≤±1%

Table-4(3)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
9	Climatic sequence -Dry heat	Sub-clause 4.23 Sub-clause 4.23.2 Test temperature: +155 °C	, , , , , , , , , , , , , , , , , , , ,
	-Damp heat, cycle (12+12hour cycle) First cycle -Cold	Duration: 16 h Sub-clause 4.23.3 Test method: 2 Test temperature: 55 °C [Severity(2)] Sub-clause 4.23.4 Test temperature –55 °C	
	-Damp heat, cycle (12+12hour cycle) Remaining cycle -D.C. load	Duration: 2h Sub-clause 4.23.6 Test method: 2 Test temperature: 55 °C [Severity (2)] Number of cycles: 5 cycles Sub-clause 4.23.7	
	-D.O. Idad	The applied current shall be the rated current.  Duration: 1 min.  Visual examination  Resistance	No visible damage ΔR≤±5%
10	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3	
	Endurance at 70 °C	Sub-clause 4.25.1 Ambient temperature: 70 °C±2 °C Duration: 1000 h The current shall be applied in cycles of 1.5 h on and 0.5 h. The applied current shall be the rated current Examination at 48 h, 500 h and 1000 h: Visual examination	
		Resistance	No visible damage ΔR≤±5%

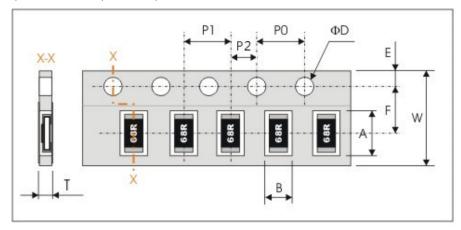


Table-4(4)

	Table—4(4)							
No	Test items	Condition of test (JIS C 5201-1)	Performance requirements					
11	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3						
	Variation of resistance with temperature	Sub-clause 4.8 +20 °C / +155 °C	As in Table–1					
12	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3						
	Damp heat, steady state	Sub-clause 4.24 Ambient temperature: 40 °C±2 °C Relative humidity: 93 ½ % Without current applied. Visual examination	No visible damage Legible marking					
13	Dimensions (detail)	Resistance Sub-clause 4.4.3	ΔR≤±5% As in Table–4					
13	Mounting	Sub-clause 4.4.3  Sub-clause 4.31  Substrate material: Epoxide woven glass Test substrate: Figure–3	AS III Table—4					
	Endurance at upper category temperature	Sub-clause 4.25.3 Ambient temperature:155 °C±2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination Resistance	No visible damage ΔR≤±5%					

#### **PACKAGING**

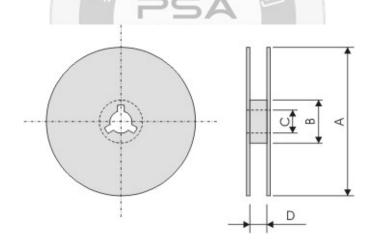
#### Plastic Tape specifications (unit :mm)



Symbol	А	В	W	F	E	
Dimensions	6.75±0.20	3.50±0.20	12.00±0.30	5.50±0.10	1.75±0.10	
X 新月 / 10 2						

130 11						
Symbol	P1	P0	P2	ΦD	Т	
Dimensions	4.00±0.10	4.00±0.10	2.00±0.10	$\Phi 1.50^{+0.1}_{-0.0}$	0.90±0.20	

#### **Reel dimensions**



Symbol	Α	В	С	D
(unit : mm)	Ф180.0 -1.5	Φ60.0±1.0	13.0±0.2	13.0±1.0

## **Taping quantity**

- Chip resistors 4,000 pcs per reel.

# **Mouser Electronics**

**Authorized Distributor** 

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Walsin:

WW25Q\_FTL WW25Q\_JTL